

Statement of Compliance

Requested Part

TE Internal Numbers502156-6Product Description// UNIV HDR 26P VERTPart Status// ConvertMil-Spec CertifiedNoEU ROHS Directive 2011/65/EUCompliantThis dectaration covers EU Directive 2011/65/EU incl. Delegated DirectiveCompliant2000/53/ECCompliantEU RELV DirectiveCompliant2000/53/ECSolder Process Capability ConMill T Order No 32, 2016Immet China RoHS 2 DirectiveEU REACH RegulationCurrent ECHA Candidate List: JAN 2023 (233) Des not contain REACH SVHCKeine Alagen ContettNot Low Halogen - contains Br or Cl > 900 ppm.Material DeclarationMile Stol2156-6 Hole Stol2166-6 Hole Stol2166-6	12 June 2023	510215	6-6	(Part 1 of 1)
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Material Declarations: MD_5102156-6		Halogen Content:	Not Low Halogen - contains Br or Cl	> 900 ppm.
	So	der Process Capability Code:	Wave solder capable to 265°C	
MD_5102156-6		Material Declarations:	MD_5102156-6	
			MD_5102156-6	

TE Connectivity Corporation

1050 Westlakes Drive

Berwyn, PA 19312

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change.

The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked.

Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV).

Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

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